

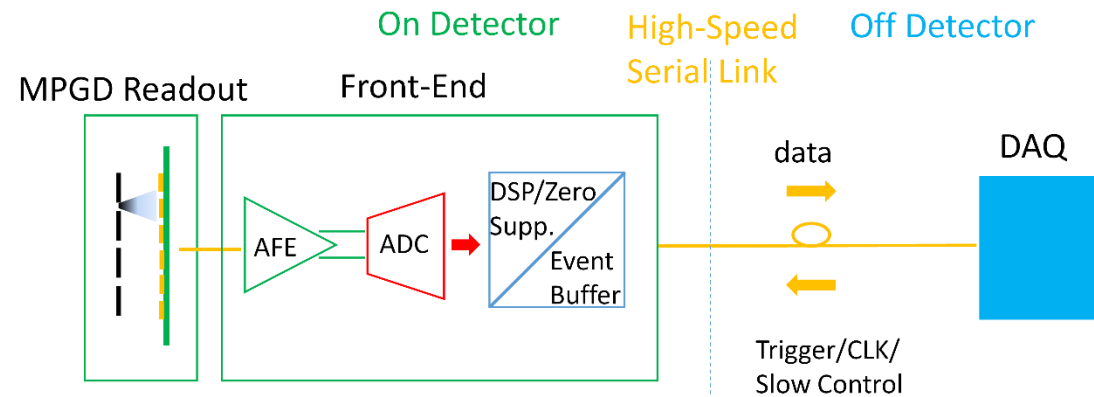
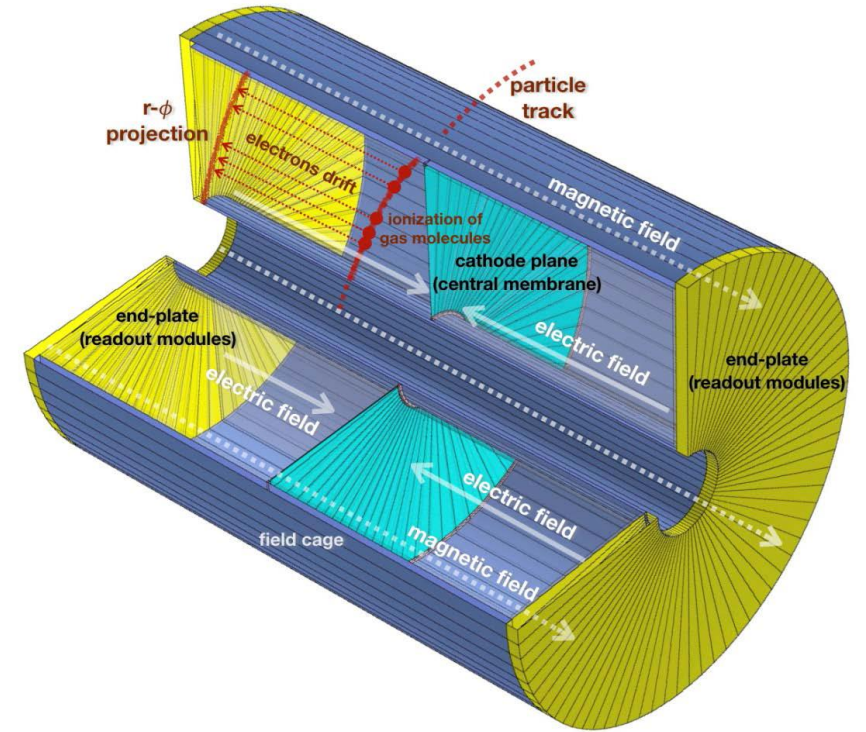
Tpc electronics TDR

Zhi Deng

02/01/2024

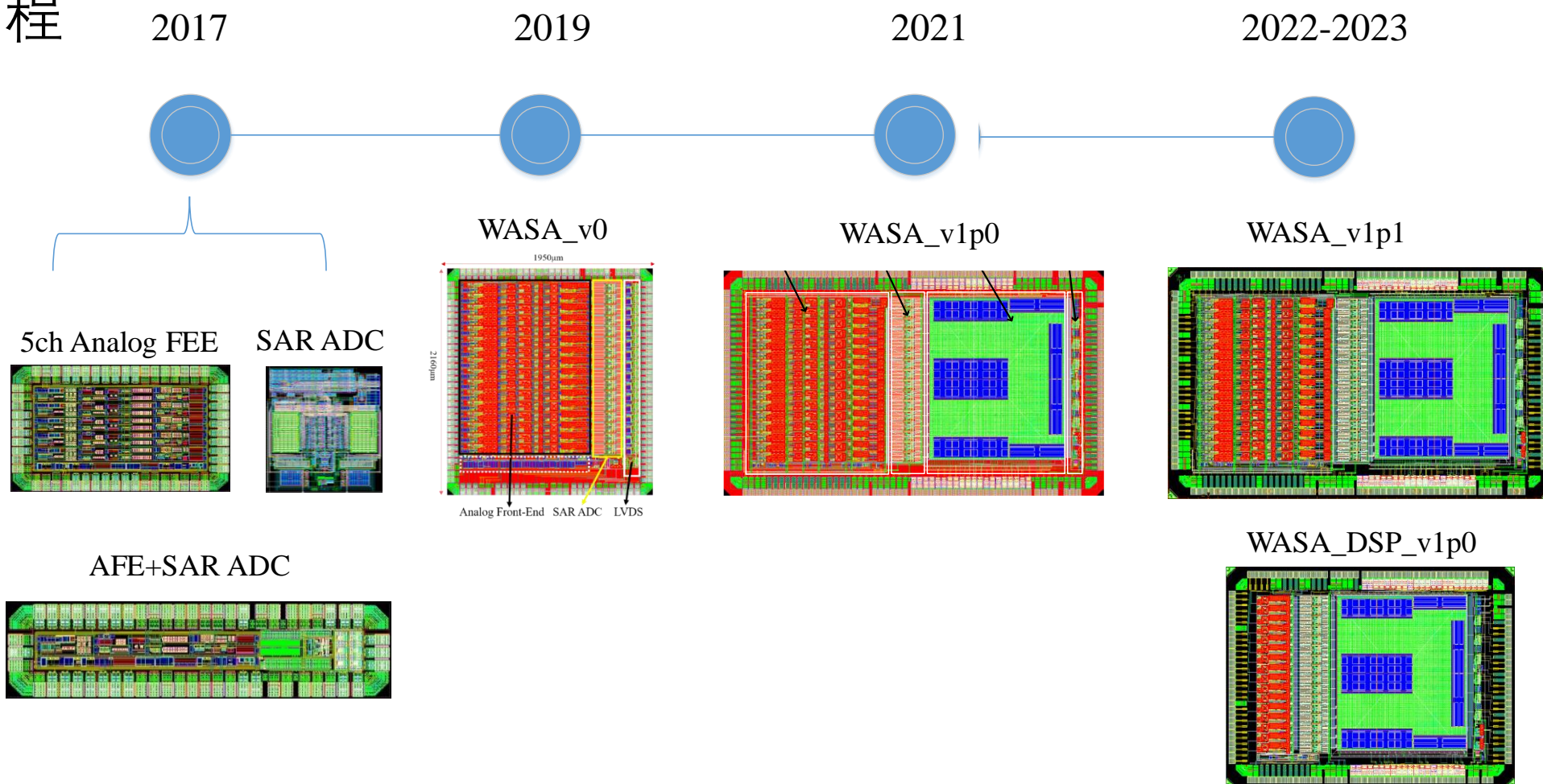
TPC Electronics

- 主要指的是front-end部分，不包含DAQ
- 探测器方案
 - pad readout, pixel readout, 两者皆有（空间、时间？）
 - 制冷：two phase CO₂?
- DAQ
 - 接口：类似gbit的方案？
 - 如何扩展：模块化

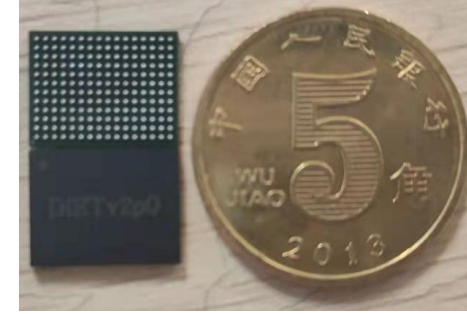


已有基础： WASA

- 研制历程



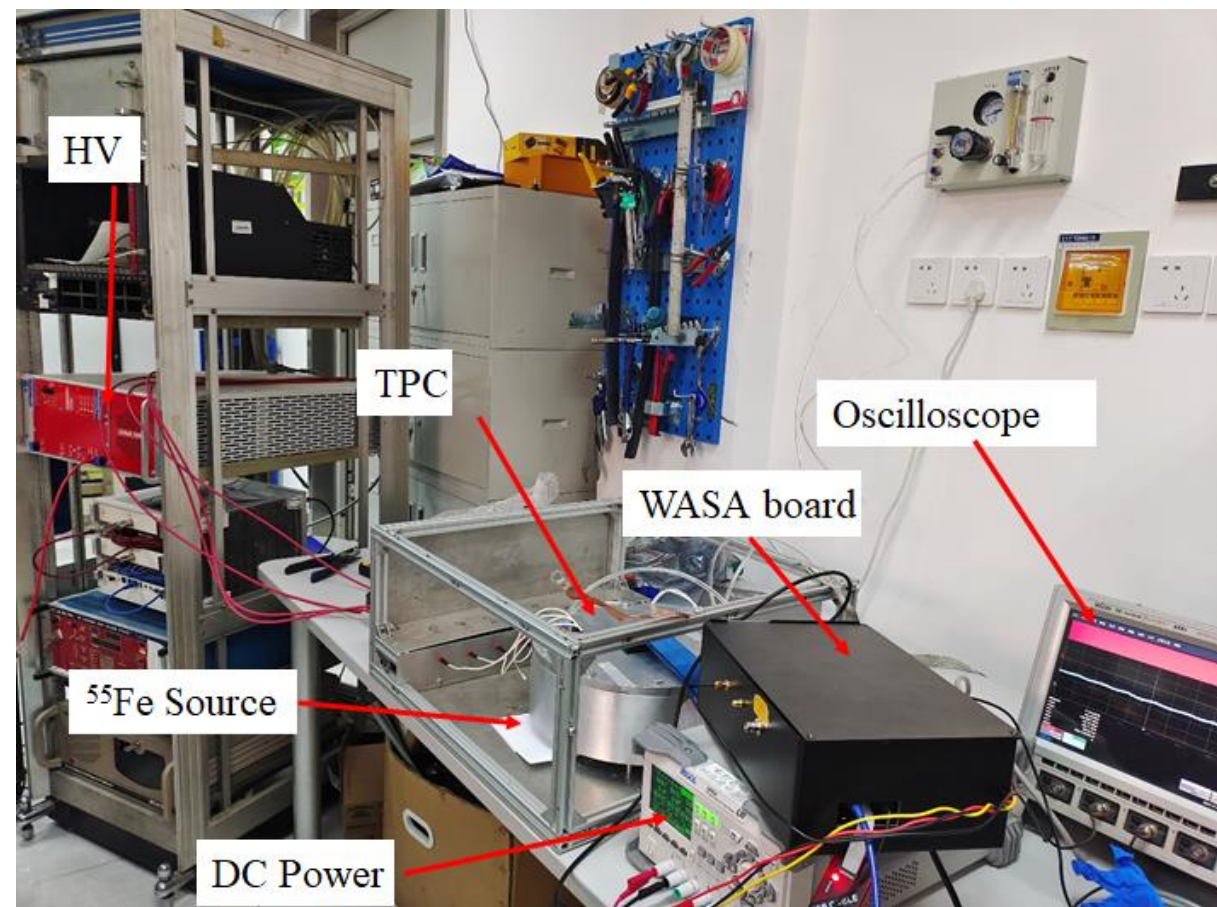
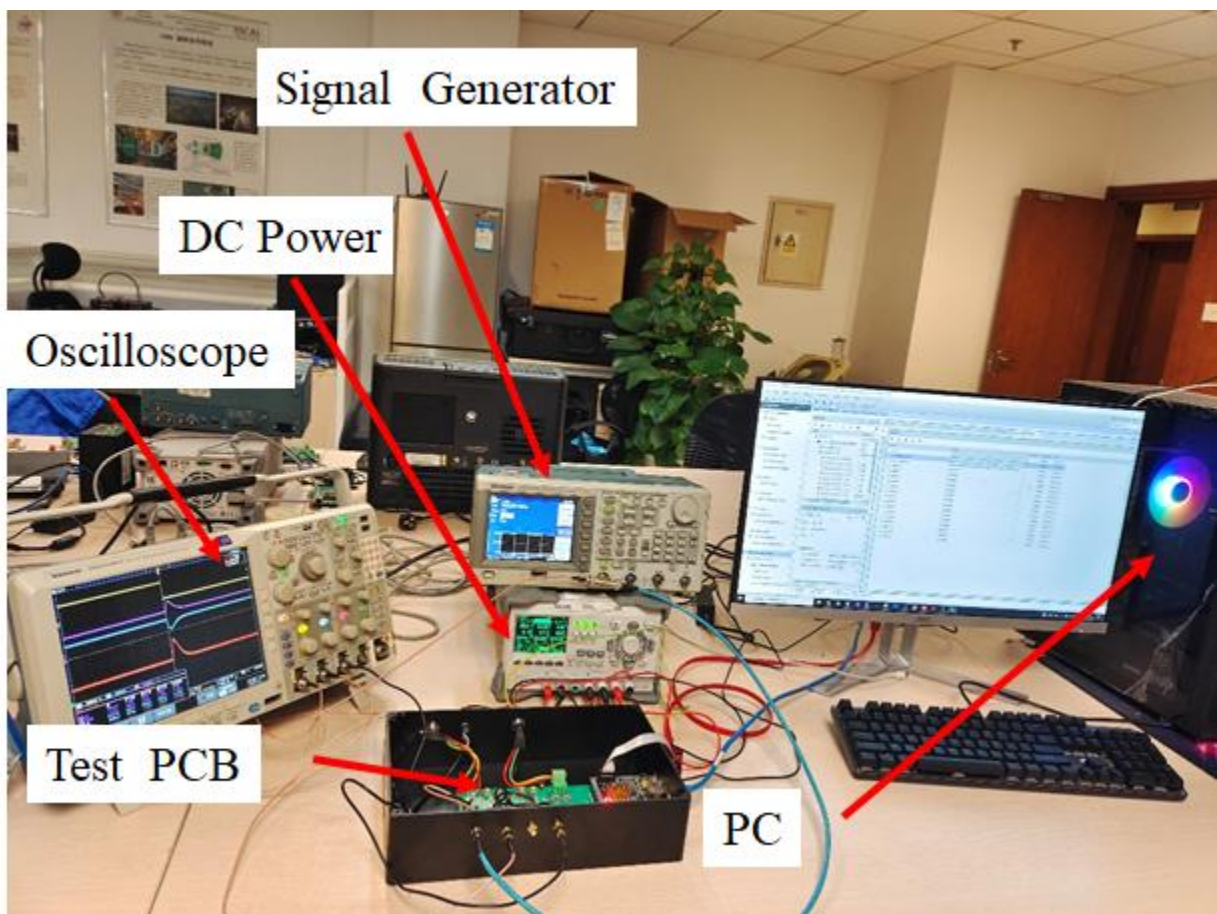
已有基础： WASA



	PASA+ALTRO	Super-ALTRO	SAMPA	WASA
TPC	ALICE	ILC	ALICE upgrade	CEPC
Pad size	4x7.5 mm ²	1x6 mm ²	4x7.5 mm ²	1x6 mm ²
Number of channels	5.7 × 10 ⁵	1-2 × 10 ⁶	5.7 × 10 ⁵	2 x × 10 ⁶
Readout detector	MWPC	GEM/MicroMegas	GEM	GEM/MicroMegas
Gain	12 mV/fC	12-27 mV/fC	20/30 mV/fC	10-40 mV/fC
Shaper	CR-(RC) ⁴	CR-(RC) ⁴	CR-(RC) ⁴	CR-RC
Peaking time	200 ns	30-120 ns	80/160 ns	160-400 ns
ENC	370+14.6 e/pF	520 e	246+36 e/pF	569+14.8 e/pF
Sampler	Pipeline ADC	Pipeline ADC	SAR ADC	SAR ADC
Sampling rate	10 MHz	40 MHz	10 MHz	10-100 MHz
Resolution	10 bit	10 bit	10 bit	10 bit
Power (ana.)	11.7 mW/ch	10.3 mW/ch	9 mW/ch	1.4 mW/ch
Power (ADC)	12.5 mW/ch	33 mW/ch	1.5 mW/ch	0.8 mW/ch@40 MHz
Power (digital)	7.5 mW/ch	4.0 mW/ch	6.5 mW/ch	2.7 mW/ch@40 MHz
Total Power	31.7 mW/ch@10MHz	47.3 mW/ch@40 MHz	17 mW/ch@10 MHz	4.9 mW/ch@40 MHz
CMOS Process	250 nm	130 nm	130 nm	65 nm

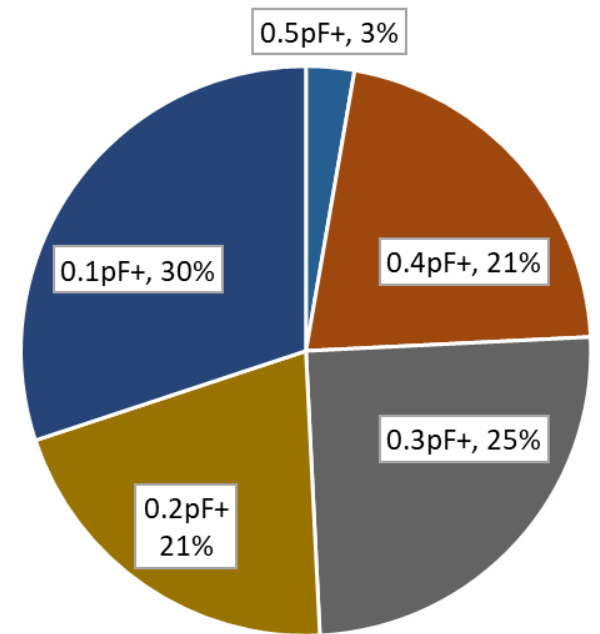
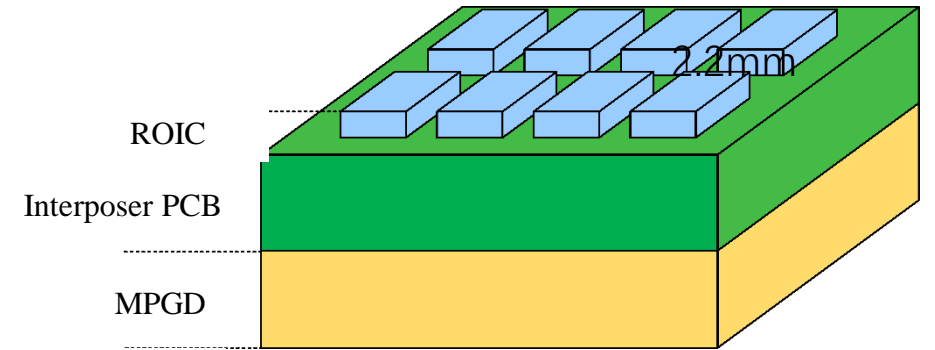
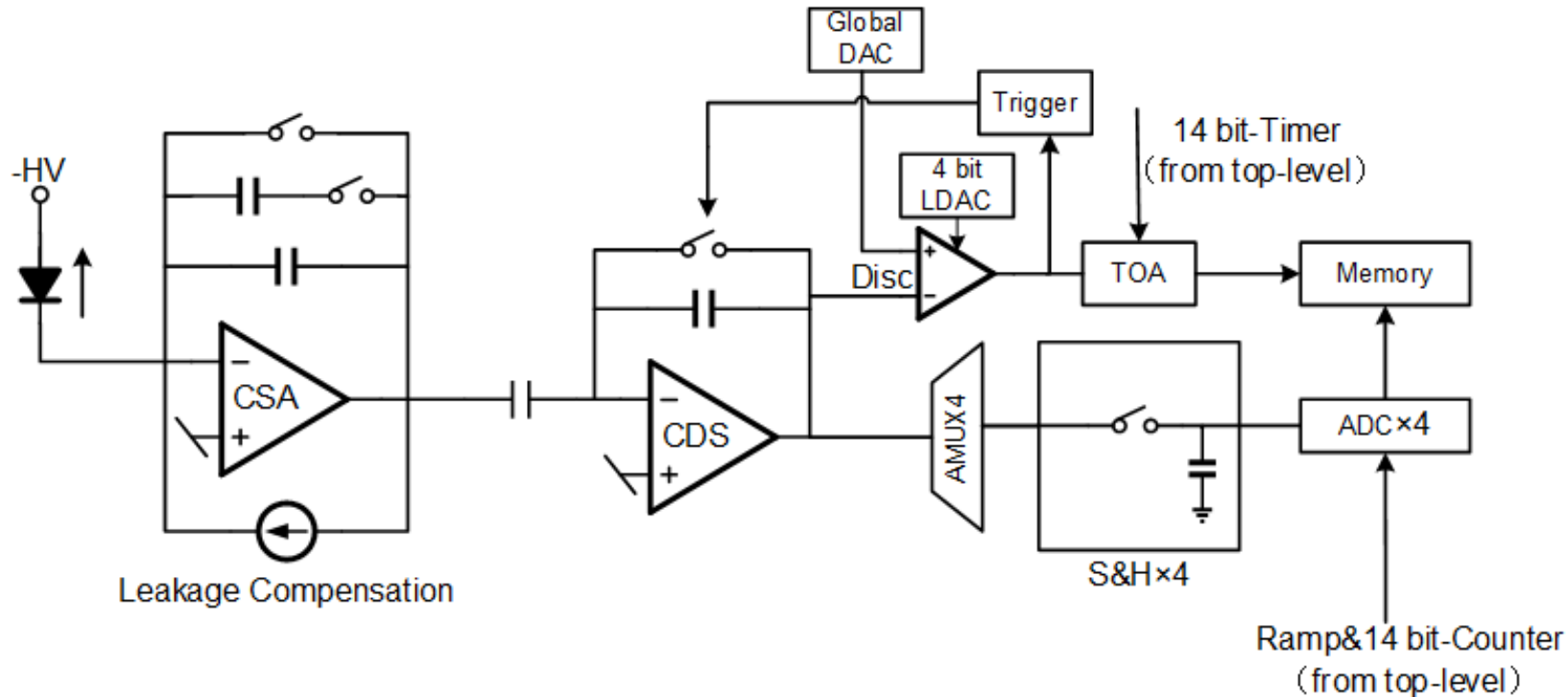
已有基础: WASA

- 测试



已有基础

- Mini-pad or pixel readout



工作计划

- TPC前端读出电子学模块的研制
 - pad读出的TDR方案: ~1k通道规模, 探测器?
 - Mini-pad or pixel读出的TDR方案: 32x32阵列的模块
- 芯片迭代
 - 定型前还需要1轮mpw
- TDR撰写
 - 参考LCTPC, 提供一个初版
 - 组织和TPC探测器和DAQ的讨论